

30V P-Channel Enhancement Mode MOSFET

Description	Schematic diagram
<p>The CP75P03G uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications.</p>	
General Features	Marking and pin assignment
<ul style="list-style-type: none"> ◆ $V_{DS} = -30V$, $I_D = -75A$ $R_{DS(ON)}(\text{Typ.}) = 6.3m\Omega$ @ $V_{GS} = -10V$ $R_{DS(ON)}(\text{Typ.}) = 10.1m\Omega$ @ $V_{GS} = -4.5V$ High power and current handling capability ◆ Lead free product is acquired ◆ Surface mount package 	
Application	XXXX—Wafer Information YYYY—Quality Code
<ul style="list-style-type: none"> ◆ Load switch 	
Package	
<ul style="list-style-type: none"> ◆ TO-252-2L 	

Ordering Information

Part Number	Storage Temperature	Package	Devices Per Reel
CP75P03G-G	-55°C to +150°C	TO-252-2L	2500

Absolute Maximum Ratings (TA=25°C unless otherwise noted)

parameter	symbol	limit	unit
Drain-source voltage	V_{DS}	-30	V
Gate-source voltage	V_{GS}	± 20	V
Continuous Drain Current	$TC=25^\circ C$	I_D	A
	$TC=100^\circ C$		
Pulsed Drain Current	I_{DP}	-300	A
Avalanche energy ($L=0.5mH$)	E_{AS}	266	mJ
Maximum power dissipation	$TC=25^\circ C$	P_D	W
	$TC=70^\circ C$		
Operating junction Temperature range	T_j	-55—150	°C

Electrical Characteristics (TA=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Static Characteristics						
Drain-source breakdown voltage	BV _{DSS}	V _{GS} =0V, I _D =-250μA	-30	-	-	V
Zero gate voltage drain current	I _{DSS}	V _{DS} =-30V, V _{GS} =0V	-	-	-1	μA
		T _J =55°C	-	-	-5	
Gate Leakage Current	I _{GSS}	V _{DS} =0V, V _{GS} =±20V	-	-	±100	nA
Gate threshold voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =-250μA	-1	-1.6	-2.5	V
Drain-source on-state resistance ¹	R _{DS(ON)}	V _{GS} =-10V, I _D =-10A	-	6.3	8	mΩ
		V _{GS} =-4.5V, I _D =-10A	-	10.1	13	
On Status Drain Current	I _{D(ON)}	V _{DS} =-10V, V _{GS} =-10V	-75	-	-	A
Diode Characteristics						
Diode Continuous Forward Current	I _S		-	-	-75	A
Reverse Recovery Time	t _{rr}	I _F =-20A, dI/dt=100A/us	-	16	-	ns
Reverse Recovery Charge	Q _{rr}		-	33	-	nC
Dynamic Characteristics²						
Gate Resistance	R _G	V _{GS} =0V, V _{DS} =0V, f=1MHz	-	4.8	-	Ω
Input capacitance	C _{iss}	V _{GS} =0V, V _{DS} =-15V f=1.0MHz	-	3042	-	pF
Output capacitance	C _{oss}		-	383	-	
Reverse transfer capacitance	C _{rss}		-	356	-	
Turn-on delay time	t _{D(ON)}	V _{GS} =-5V, V _{DS} =-15V, R _L =20Ω, I _D =-10A, R _G =6Ω	-	12	-	ns
Turn-on Rise time	t _r		-	22	-	
Turn-off delay time	t _{D(OFF)}		-	36	-	
Turn-off Fall time	t _f		-	24	-	
Total gate charge	Q _g	V _{GS} =-5V, I _D =-10A V _{DS} =-15V	-	35.1		nC
Gate-source charge	Q _{gs}			20		
Gate-drain charge	Q _{gd}		-	5.7	-	
Drain-Source Diode Characteristics						
Diode forward voltage	V _{SD}	I _{SD} =-10A, V _{GS} =0V	-	-0.81	-1.5	V

Note: 1: Pulse test; pulse width ≤ 300ns, duty cycle ≤ 2%.

2: Guaranteed by design, not subject to production testing.

Typical Performance Characteristics

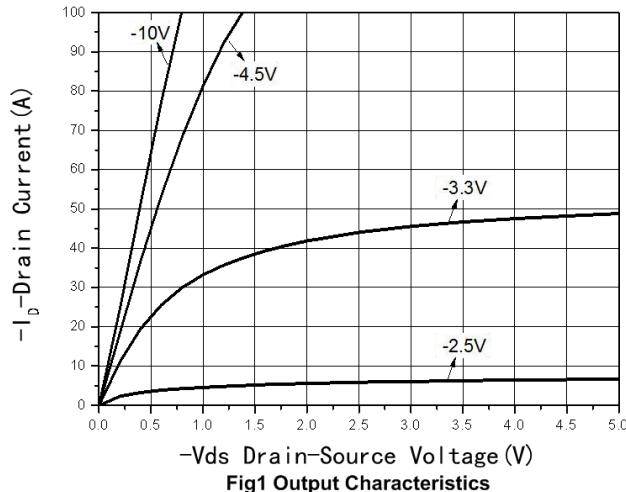


Fig1 Output Characteristics

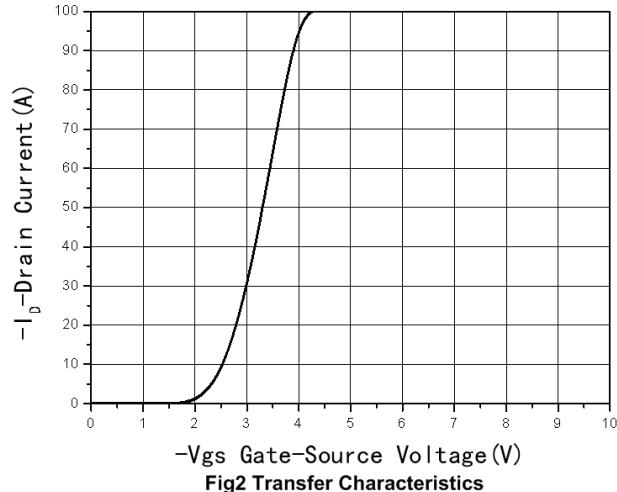


Fig2 Transfer Characteristics

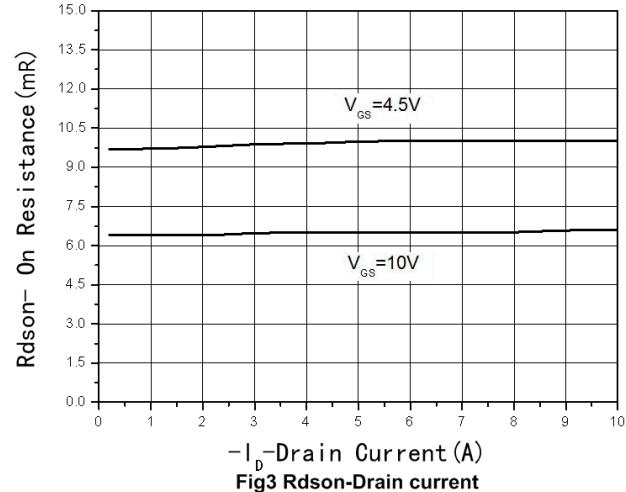


Fig3 Rdson-Drain current

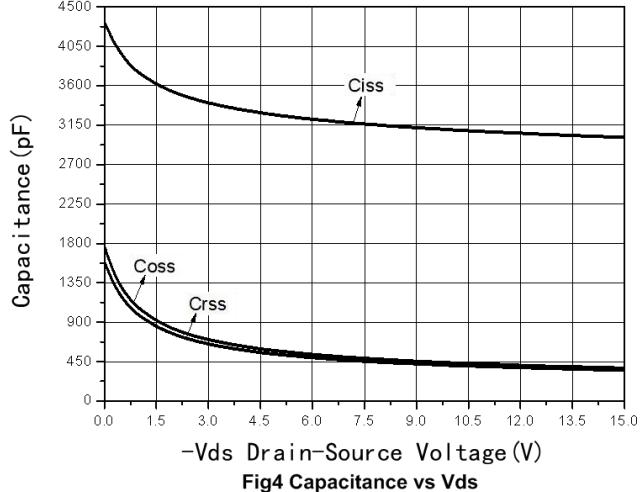


Fig4 Capacitance vs Vds

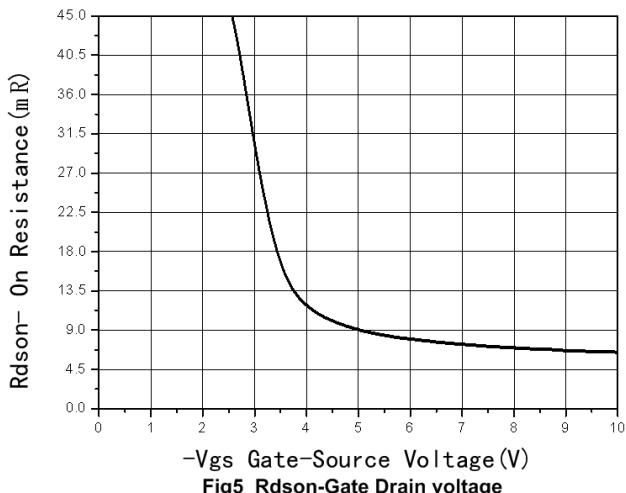


Fig5 Rdson-Gate voltage

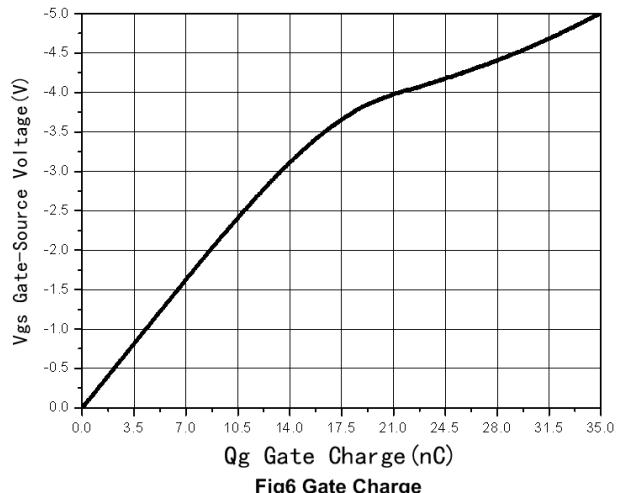


Fig6 Gate Charge

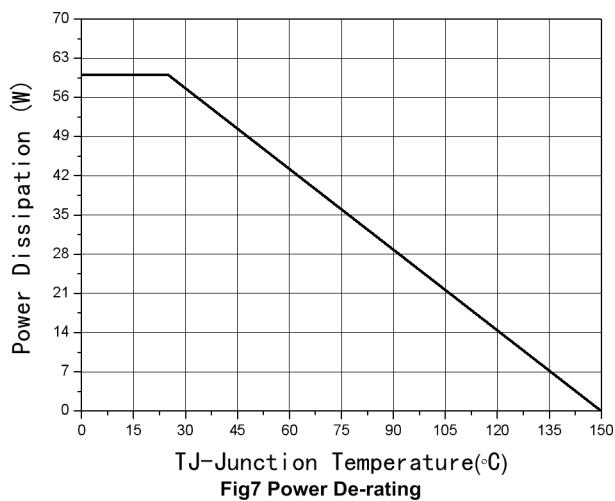


Fig7 Power De-rating

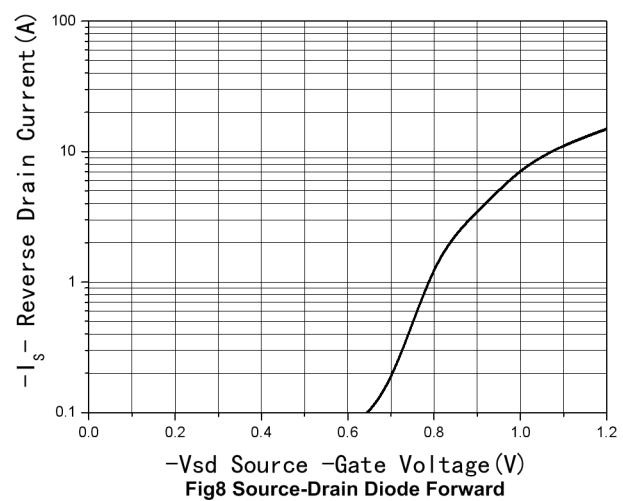
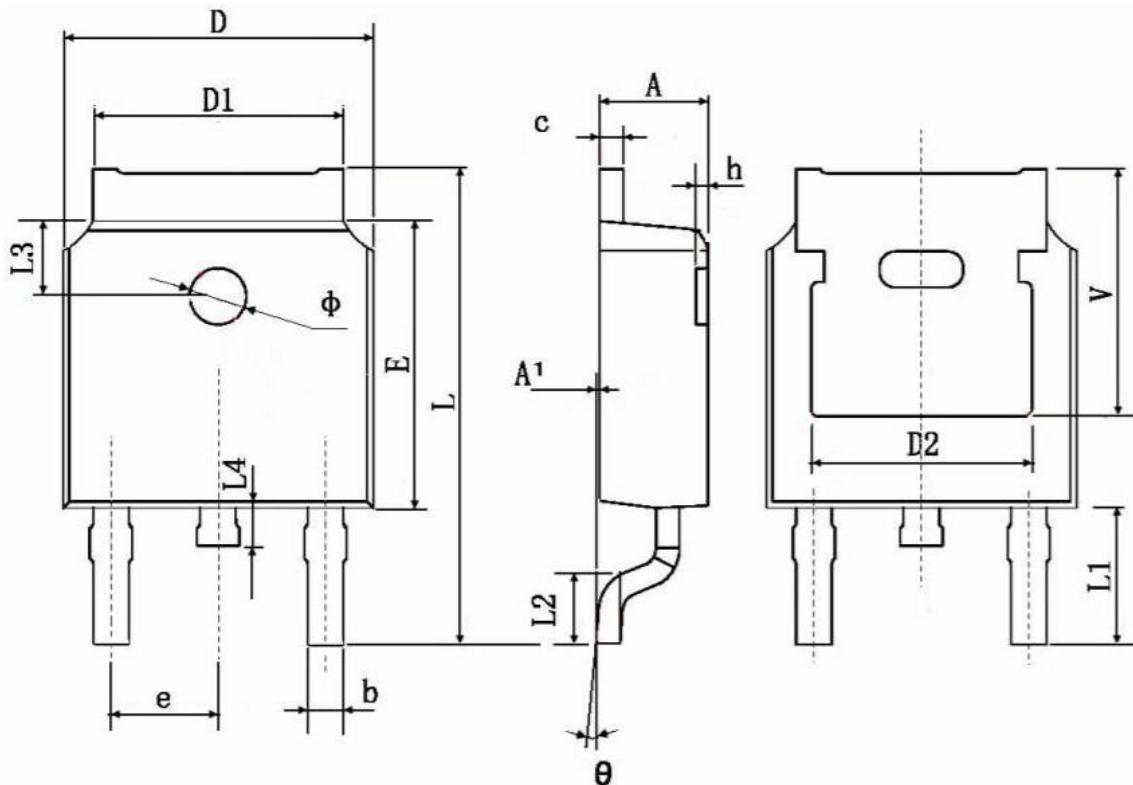


Fig8 Source-Drain Diode Forward

Package Information

- TO-252-2L



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
b	0.660	0.860	0.026	0.034
c	0.460	0.580	0.018	0.023
D	6.500	6.700	0.256	0.264
D1	5.100	5.460	0.201	0.215
D2	4.830 TYP.		0.190 TYP.	
E	6.000	6.200	0.236	0.244
e	2.186	2.386	0.086	0.094
L	9.800	10.400	0.386	0.409
L1	2.900 TYP.		0.114 TYP.	
L2	1.400	1.700	0.055	0.067
L3	1.600 TYP.		0.063 TYP.	
L4	0.600	1.000	0.024	0.039
Φ	1.100	1.300	0.043	0.051
θ	0°	8°	0°	8°
h	0.000	0.300	0.000	0.012
V	5.350 TYP.		0.211 TYP.	